

Title (en)

ARTIFICIAL NAIL AND METHOD FOR APPLYING SAME

Title (de)

KÜNSTLICHERNAGEL UND VERFAHREN ZUM ANBRINGEN DERSELBEN

Title (fr)

ONGLE ARTIFICIEL ET PROCEDE D'APPLICATION

Publication

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Application

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Abstract (en)

[origin: WO0200057A2] An artificial fingernail, fingernail kit and a method of applying the artificial fingernails to natural nails. The artificial fingernail includes a nail body made from transparent plastic and having a nail bed portion and a nail tip portion. The nail bed portion substantially corresponds to the nail bed of a natural fingernail and is applied over a natural fingernail. The nail tip portion includes a continuous opaque decoration which obscures a natural nail tip when the artificial fingernail is applied over a natural fingernail. The nail bed portion is substantially transparent allowing the natural nail bed to be visible therethrough.

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A45D 31/00

IPC 8 full level

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Citation (search report)

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- [X] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 12 25 December 1997 (1997-12-25)
- See references of WO 0200057A2

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